

Title (en)

NANOPOROUS MATERIALS AND METHODS OF FORMATION THEREOF

Title (de)

NANOPORRÖSE MATERIALIEN UND VERFAHREN ZU IHRER HERSTELLUNG

Title (fr)

MATIERES NANOPOREUSES ET PROCEDES DE FORMATION ASSOCIES

Publication

EP 1535290 A4 20060614 (EN)

Application

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Priority

US 0226276 W 20020815

Abstract (en)

[origin: WO2004017335A1] Low dielectric materials are described herein that comprise a plurality of pores or nanopores in addition to the ultrananopores. It is further contemplated that the low dielectric materials described herein will have a dielectric constant of less than about 3. The dielectric materials are formed from polymer compositions, wherein the polymer compositions comprise a plurality of monomers and wherein at least one monomer comprises a radical precursor bonded to a structural precursor. Further, methods of forming dielectric materials from polymer compositions are presented. The figure shows the chemical structure for a methyl/t-butyl Low Organic Content/Low Organic Siloxane Polymer.

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IPC 8 full level

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Citation (search report)

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- [X] WO 0129052 A1 20010426 - ALLIED SIGNAL INC [US]
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- See also references of WO 2004017335A1

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TW 91121145 A 20020916; US 52025202 A 20020815